




<div>MICROCHIP</div>						Package Homogeneous Materials				
Semiconductor Device Type:			H7X	LQFP_100_14x14x1.4mm_MatteTin						
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	17.00	(mg) Total	Die	% of Total Weight	2.49
Silicon (Si)	7440-21-3	Die	2.49	17.00	24916		Silicon (Si)	7440-21-3	100.00	
Copper (Cu)	7440-50-8	Leadframe	22.25	151.81	222494	Total 100.00				
Iron (Fe)	7439-89-6	Leadframe	0.54	3.66	5363					
Zinc (Zn)	7440-66-6	Leadframe	0.03	0.19	274	160.80	(mg) Total	Leadframe	% of Total Weight	23.57
Metallic Phosphorus (P)	7723-14-0	Leadframe	0.01	0.05	68	C194 ESH	Copper (Cu)	7440-50-8	94.41	
Silver (Ag)	7440-22-4	Leadframe	0.75	5.10	7475		Iron (Fe)	7439-89-6	2.28	
Silver (Ag)	7440-22-4	Die Attach	0.12	0.84	1236		Zinc (Zn)	7440-66-6	0.12	
2,2'-(Methylenebis(phenyleneoxymethylene))bisoxirane	39817-09-9	Die Attach	0.01	0.08	121		Metallic Phosphorus (P)	7723-14-0	0.03	
Organic anhydride	26544-38-7	Die Attach	0.01	0.08	121	Plating	Silver (Ag)	7440-22-4	3.17	
1,3-Di-2-propenyl-2- (2-propenyloxy) benzene, epoxidized	Trade Secret	Die Attach	0.00	0.03	48	Total 100.00				
Epoxide	3234-28-4	Die Attach	0.00	0.03	48					
1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	Die Attach	0.00	0.02	28	1.10	(mg) Total	Die Attach	% of Total Weight	0.16
Copper oxide	1317-38-0	Die Attach	0.00	0.00	2	3230	Silver (Ag)	7440-22-4	76.65	
Maleic anhydride	108-31-6	Die Attach	0.00	0.01	8		2,2'-(Methylenebis(phenyleneoxymethylene))bisoxirane	39817-09-9	7.50	
Gold (Au)	7440-57-5	Bonding Wire	0.47	3.20	4690		Organic anhydride	26544-38-7	7.50	
Other	Trade Secret	Bonding Wire	0.00	0.00	0		1,3-Di-2-propenyl-2- (2-propenyloxy) benzene, epoxidized	Trade Secret	3.00	
Epoxy Resin A	Trade Secret	Mold Compound	0.73	4.95	7261		Epoxide	3234-28-4	3.00	
Epoxy Resin B	Trade Secret	Mold Compound	0.73	4.95	7261		1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	1.75	
Phenol Resin	Trade Secret	Mold Compound	3.63	24.77	36304		Copper oxide	1317-38-0	0.10	
Silica(Amorphous) A	60676-86-0	Mold Compound	59.54	406.23	595380		Maleic anhydride	108-31-6	0.50	
Silica(Amorphous) B	7631-86-9	Mold Compound	7.26	49.54	72607	Total 100.00				
Carbon Black	1333-86-4	Mold Compound	0.73	4.95	7261					
Tin (Sn)	7440-31-5	Lead Finish	0.70	4.80	7035	3.20	(mg) Total	Bonding Wire	% of Total Weight	0.47
TOTALS:			100.00	682.30	1,000,000	Au HP Wire (4N)	Gold (Au)	7440-57-5	99.99	
682.30 mg Total Mass							Other	Trade Secret	0.01	

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